

Bi-directional Ultra Low Capacitance TVS Diode

• ESD / transient protection of RF signal

lines according to:

IEC61000-4-2 (ESD): ±20kV (contact)

IEC61000-4-4 (EFT): 40 A (5 / 50 ns)

IEC61000-4-5 (Surge): 3 A (8 / 20 μs)

 Extremely small form factor down to 0.62 x 0.32 x 0.31 mm³

- Very low dynamic resistance
- Max. working voltage: ±5.3 V
- Extremely low capacitance: 0.2 pF typ.
- Very low reverse current < 1 nA typ.
- Very low series inductance down to 0.2 nH typ.
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

Applications

- ESD protection of sensitive RF signal lines
- RF antenna protection, frontend module
- GPS, mobile TV, FM radio, RKE, UWB





ESD0P2RF-02LRH ESD0P2RF-02LS



Туре	Package	Configuration	Marking
ESD0P2RF-02LRH	TSLP-2-17	1 line, bi-directional	Т
ESD0P2RF-02LS	TSSLP-2-1	1 line, bi-directional	Т

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Maximum Ratings at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾ , contact	V _{ESD}	20	kV
Peak pulse current ($t_p = 8 / 20 \mu s)^{2}$	I _{pp}	3	Α
Operating temperature range	T_{op}	-55125	°C
Storage temperature	$T_{\rm stg}$	-55150	

 $^{^{1}}V_{\mathrm{ESD}}$ according to IEC61000-4-2

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics -	•	•			
Reverse working voltage	V_{RWM}	-5.3	-	5.3	V
Breakdown voltage	$V_{(BR)}$				
$I_{(BR)}$ = 1 mA, from pin 2 to 1		7	-	-	
$I_{(BR)}$ = 1 mA, from pin 1 to 2		7	-	-	
Reverse current	I _R	-	<1	50	nA
V _R = 5.3 V					
Clamping voltage	V_{CL}				V
$I_{PP} = 1 \text{ A}, t_p = 8/20 \ \mu \text{s}^{1)}$		-	11	17	
$I_{PP} = 3 \text{ A}, t_p = 8/20 \ \mu\text{s}^{1)}$		-	15	21	
Diode capacitance	C _T				pF
$V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$		-	0.23	0.4	
$V_{R} = 0 \text{ V}, f = 1 \text{ GHz}$		-	0.2	0.4	
Dynamic resistance (tp=30ns)	R_{D}		1	-	Ω
Series inductance	LS				nН
ESD0P2RF-02LS		_	0.2	_	
ESD0P2RF-02LRH		-	0.4	_	

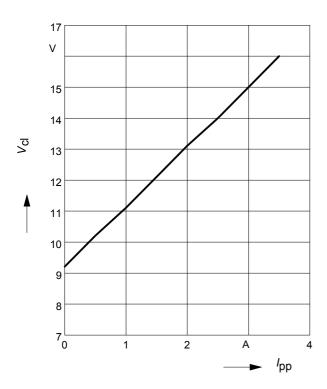
 $^{^{1}}I_{pp}$ according to IEC61000-4-5

 $^{^2}I_{\rm pp}$ according to IEC61000-4-5



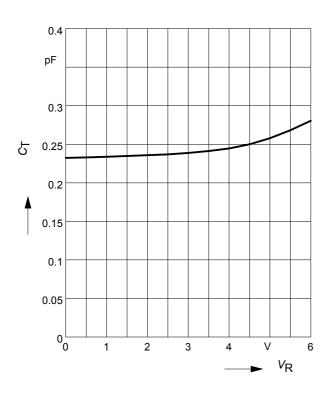
Clamping voltage, $V_{cl} = f(I_{pp})$

$$t_{\rm p}$$
 = 8 / 20 µs



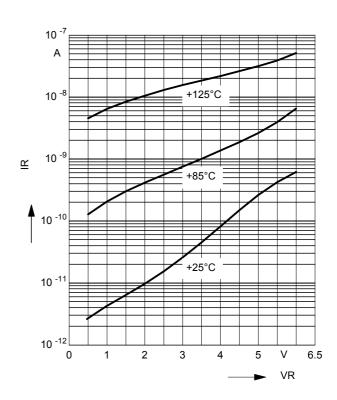
Diode capacitance $C_T = f(V_R)$

$$f = 1MHz$$



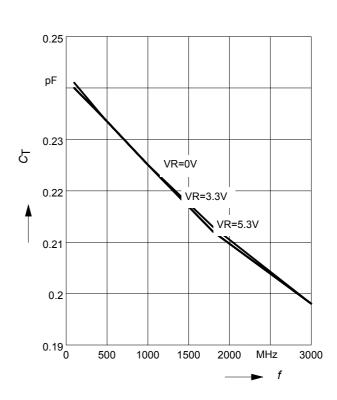
Reverse current $I_R = f(V_R)$

T_A = Parameter



Line capacitance $C_T = f(f)$

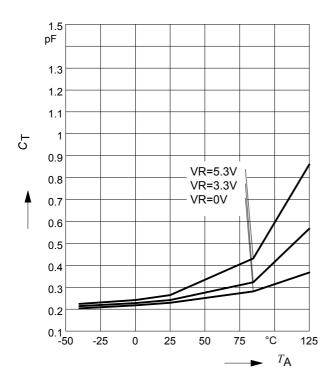
$$V_{R}$$
 = Parameter





Line capacitance $C_T = f(T_A)$

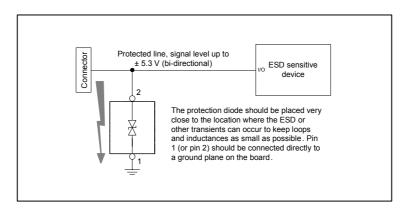
 V_{R} = Parameter, f = 1 MHz





Application example ESD0P2RF...

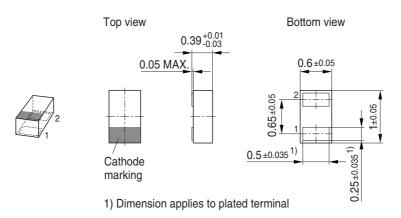
1 line, bi-directional



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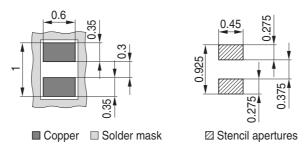


Package Outline

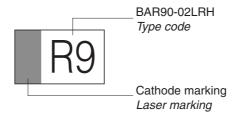


Foot Print

For board assembly information please refer to Infineon website "Packages"

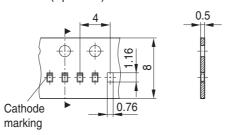


Marking Layout (Example)



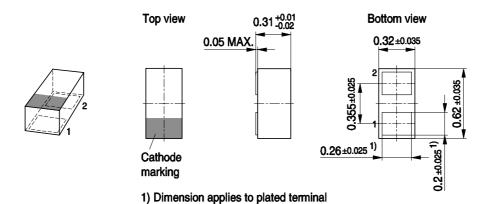
Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)



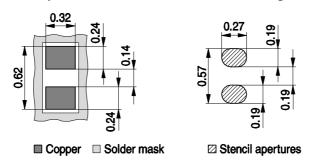


Package Outline

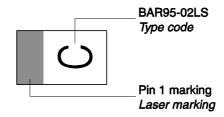


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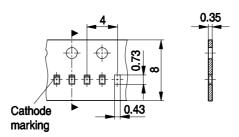


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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